

AMENDMENTS TO THE CLAIMS

1. (Canceled)
2. (Currently Amended) The capacitor of claim † 9 wherein the composite portion comprises glass sintered with the ceramic dielectric portion.
3. (Currently Amended) The capacitor of claim † ~~characterized by feature (a)~~ 9 wherein the composite portion comprises a matrix of the ceramic, and particles of the conductive metal are dispersed in the matrix, and wherein the conductive metal particles comprise about 40-90% of the composite portion.
- 4-5. (Canceled)
6. (Currently Amended) The capacitor of claim † ~~characterized by feature (a) and~~ 9 further comprising a buried horizontally-oriented metallization in the dielectric portion and having at least one conductive metal-filled via extending from the buried metallization to the composite portion.
- 7-8. (Canceled)
9. (Currently Amended) The capacitor of claim 1, A capacitor comprising an essentially monolithic structure of at least one composite portion sintered with a ceramic dielectric portion, wherein the composite portion includes a ceramic and a conductive metal in an amount sufficient to render the composite portion conductive, and wherein the ceramic dielectric portion is horizontally disposed with the composite portion sintered to a bottom portion thereof, the composite portion adapted to be mounted onto a pc board, and the capacitor further comprising a metallization on a top portion of the ceramic dielectric portion, the metallization adapted to be wire bonded to a pc board.

10-11. (Canceled)

12. (Currently Amended) The capacitor of claim 10 characterized by feature (a) 23 wherein the composite end ~~blocks~~ portions comprise a matrix of the ceramic, and particles of the conductive metal are dispersed in the matrix, and wherein the conductive metal particles comprise about 40-90% of the composite end ~~blocks~~ portions.

13-22. (Canceled)

23. (Currently Amended) A surface mountable, monolithic capacitor comprising:
a center vertically-oriented ceramic dielectric portion having opposed vertical coplanar surfaces;

a pair of composite electrode end portions comprising a ceramic and a conductive metal in an amount sufficient to render the composite conductive, each end portion having an internal vertical face and a plurality of external faces, each internal vertical face co-sintered to a respective opposed vertical coplanar surface of the center ceramic dielectric portion so as to have essentially no boundary therebetween, whereby the conductive end portions are adapted to serve as electrodes for the capacitor and to provide electrical leads for attaching the capacitor to are directly mountable on metallic surface traces on a printed circuit board.

24. (Currently Amended) The capacitor of claim 23 wherein the internal faces of the composite end portions adjacent the internal vertical faces further comprise glass.

25. (Original) The capacitor of claim 23 wherein the conductive metal comprises about 90% of the composite end portions.

26. (Currently Amended) The capacitor of claim 23 further comprising at least one buried vertically-oriented metallization in the center ceramic dielectric portion intermediate the opposed coplanar surfaces, and having at least one metal-filled via extending from the buried

metallization to one of the composite end portions.

27-37. (Canceled)

38. (New) The capacitor of claim 23 wherein the composite end portions comprise glass sintered with the ceramic dielectric portion.

39. (New) The capacitor of claim 23 wherein the ceramic dielectric portion is free of internal metal electrodes.

40. (New) A surface mountable, monolithic capacitor comprising:
a center horizontally-oriented ceramic dielectric portion having opposed horizontal coplanar surfaces;
top and bottom composite electrode portions comprising a ceramic and a conductive metal in an amount sufficient to render the composite conductive, each composite electrode portion having an internal horizontal face and a plurality of external faces, each internal horizontal face co-sintered to a respective opposed horizontal coplanar surface of the center ceramic dielectric portion so as to have essentially no boundary therebetween, whereby the conductive electrode portions serve as electrodes for the capacitor and the bottom electrode portion is directly mountable on a metallic surface trace on a printed circuit board.

41. (New) The capacitor of claim 40 wherein the ceramic dielectric portion is free of internal metal electrodes.

42. (New) The capacitor of claim 40 wherein the composite electrode portions comprise glass sintered with the ceramic dielectric portion.

43. (New) The capacitor of claim 40 wherein the composite electrode portions comprise a matrix of the ceramic, and particles of the conductive metal are dispersed in the matrix, and

wherein the conductive metal particles comprise about 40-90% of the composite electrode portions.

44. (New) The capacitor of claim 40 wherein the composite end portions adjacent the internal horizontal faces further comprise glass.

45. (New) The capacitor of claim 40 wherein the conductive metal comprises about 90% of the composite end portions.

46. (New) The capacitor of claim 9 wherein the ceramic dielectric portion is free of internal metal electrodes.